

This datasheet of **Akulon® F223-D** from **Envalior** is provided by the international plastics database **CAMPUS**.

Akulon® F223-D | PA6 | Envalior

Product Texts

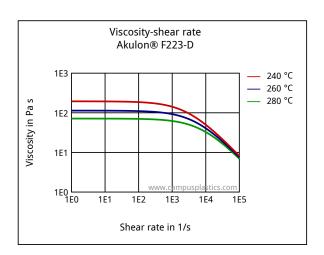
Low/Medium Viscosity, General purpose, Injection Molding, Food Contact Quality

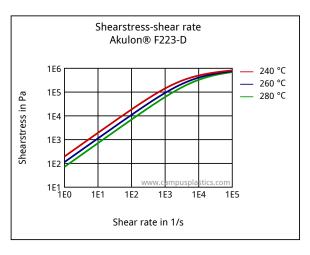
ISO 1043 PA6

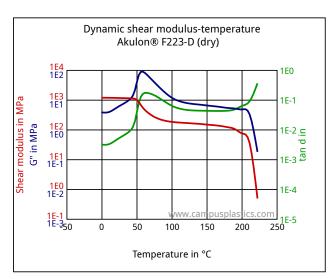
Rheological properties	dry / cond	Unit
Melt volume-flow rate, MVR	44 / *	cm³/10min
Temperature	260 / *	°C
Load	2.16 / *	kg
Molding shrinkage, parallel	1.1 / *	%
Molding shrinkage, normal	1.1 / *	%
Mechanical properties	dry / cond	Unit
Tensile modulus	3200 / 1000	MPa
Yield stress	87 / 45	MPa
Yield strain	4 / 25	%
Nominal strain at break	20 / >50	%
Charpy impact strength, +23°C	N/N	kJ/m²
Charpy impact strength, -30°C	N/N	kJ/m²
Charpy notched impact strength, +23°C	4.5 / 35	kJ/m²
Charpy notched impact strength, -30°C	2.5 / 5	kJ/m²
Thermal properties	dry / cond	Unit
Melting temperature, 10°C/min	220 / *	°C
Temp. of deflection under load, 1.80 MPa	60 / *	°C
Temp. of deflection under load, 0.45 MPa	150 / *	°C
Vicat softening temperature, 50°C/h 50N	195 / *	°C
Coeff. of linear therm. expansion, parallel	90 / *	E-6/K
Coeff. of linear therm. expansion, normal This website uses cookies. By using this website, you agr	90 / * ee to the use o	E-6/K f cookies. P

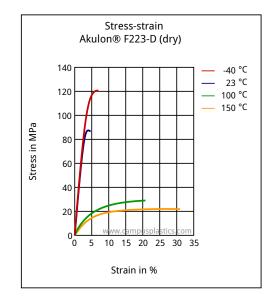
Thickness tested (1.5)	1.5 / *	mm
Yellow Card available	Yes / *	-
Burning behavior at thickness h	V-2 / *	class
Thickness tested (h)	3.0 / *	mm
Yellow Card available	Yes / *	-
FMVSS	SE/NBR	-
Oxygen index	26 / *	%
Electrical properties	dry / cond	Unit
Relative permittivity, 100Hz	3.2 / 14	-
Relative permittivity, 1MHz	3 / 4.5	-
Dissipation factor, 100Hz	50 / 3000	E-4
Dissipation factor, 1MHz	150 / 1200	E-4
Volume resistivity	1E13 / 1E10	Ohm*m
Surface resistivity	* / 1E14	Ohm
Electric strength	28 / 20	kV/mm
Comparative tracking index	* / 600	-
Other properties	dry / cond	Unit
Water absorption	10 / *	%
Humidity absorption	2.8 / *	%
Density	1130 / -	kg/m³
Material specific properties	dry / cond	Unit
Viscosity number	132 / *	cm³/g
Rheological calculation properties	Value	Unit
Density of melt	960	kg/m³
Thermal conductivity of melt	0.23	W/(m K)
Spec. heat capacity melt	2680	J/(kg K)
Eff. thermal diffusivity	8.82E-8	m²/s

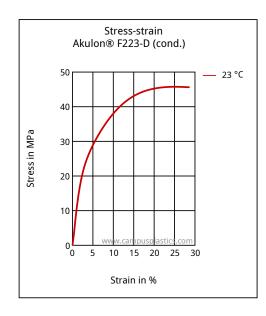
Diagrams

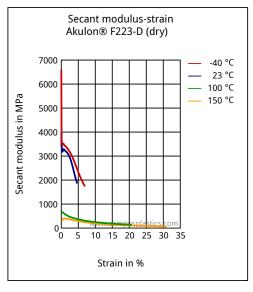


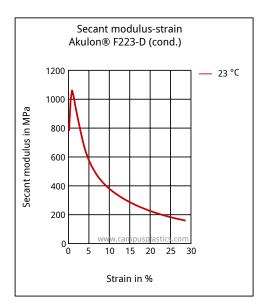


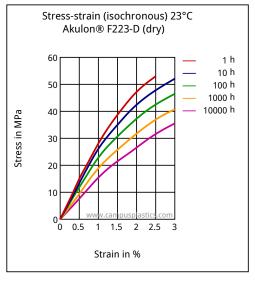


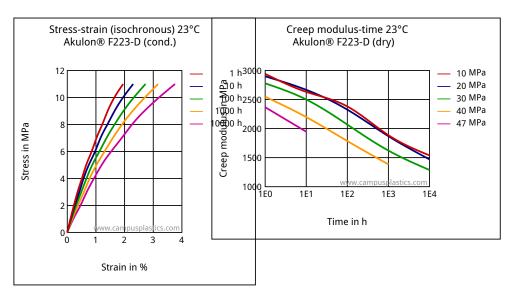


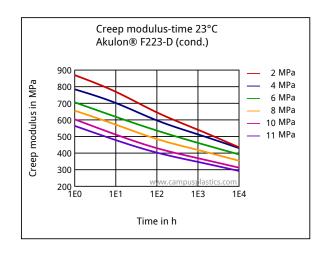


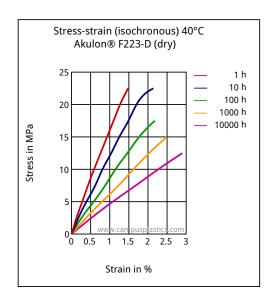


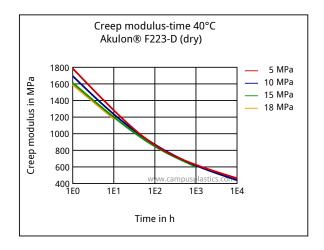


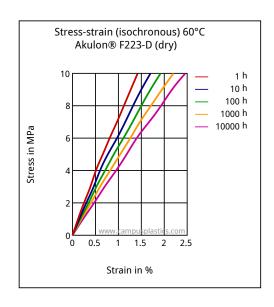


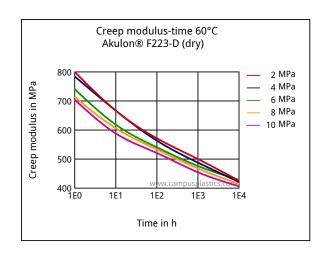


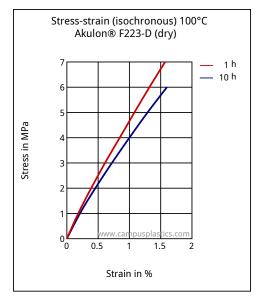


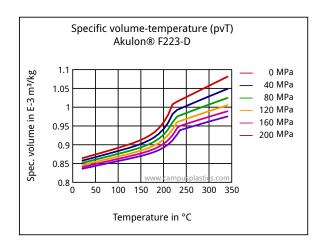












Characteristics

Processing

Injection Molding

North America, Europe, Asia Pacific

Other text information

Injection molding

Injection Molding Recommendations
Steel recommendations for molds screws and barrels
Trouble shooting guideline for injection molding

Chemical Media Resistance

Alcohols

Methanol (23°C)

Ethanol (23°C)

Hydrocarbons

Toluene (23°C)

Ketones

Acetone (23°C)

Ethers

Diethyl ether (23°C)

Other

Ethyl Acetate (23°C)

Water (23°C)

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